

REMARKS

Claims 1-9 and 32-34 are now pending in the application. Claims 10-31 are cancelled. Claims 32-34 are added. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

SPECIFICATION

The specification stands objected to for certain informalities. Applicant amends the specification to address the Examiner's concerns. Therefore, reconsideration and withdrawal of this objection are respectfully requested.

REJECTION UNDER 35 U.S.C. § 112

Claims 2-4 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point and distinctly claim the subject matter which Applicant regards as the invention. This rejection is respectfully traversed. Notwithstanding, Claim 2 is amended to remove reference to the phrase "too fine". Claims 3 and 4 depend from claim 2. Accordingly, reconsideration and withdrawal of this rejection are respectfully requested.

REJECTION UNDER 35 U.S.C. § 103

Claims 1 and 5 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Kikuchi (U.S. Publication No. 2002/0005568). This rejection is respectfully traversed.

Claim 1 calls for making a surface of a resin layer uneven by forming a plurality of recesses therein. The cited references fail to disclose this feature. For example, Kikuchi only discloses an interlayer film 140. The interlayer film 140 does not have an uneven surface including a plurality of recesses.

Claim 1 also calls for forming an interconnecting line on the resin layer that contacts the inner surfaces of the recesses. The cited references also fail to disclose this feature.

Claim 5 depends from claim 1 and should be allowable for at least the same reasons as set forth above.

Claims 2-4 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Kikuchi in view of Wolf et al. ("Silicon Processing for the VLSI Era", Vol. 1, Ch. 12, pages 407-409). This rejection is respectfully traversed.

Claims 2-4 depend (directly or indirectly) from claim 1 and should be allowable for at least the same reasons as set forth above. Further, Claim 2 calls for the resin layer to be formed of a photosensitive resin precursor and for photolithography using a mask to be applied in the step of forming the recesses. The mask includes a transparent-and-opaque pattern for carrying out light irradiation. The pattern (due to it being too fine) prevents the photosensitive resin precursor from being completely resolved. The pattern (also due to it being too fine) also prevents the recesses from penetrating the entire thickness of the resin layer. The cited references fail to disclose this feature. More particularly, Wolf et al. only discloses well-known photolithography but fails to disclose the feature recited in claim 2.

Claims 3 and 4 depend from claim 2 and should be allowable for at least the same reasons as set forth above.

Claims 6-9 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Kikuchi in view of Ma (U.S. Patent No. 6,713,859). This rejection is respectfully traversed. Claims 6-9 depend from claim 1 and should be allowable for at least the same reasons as set forth above.

NEW CLAIMS

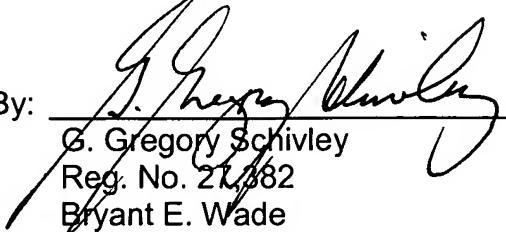
New claims 32-34 are added. Support for new claims 32-34 is found at least at Figs. 3A-3C, respectively. Favorable consideration of these new claims is respectfully requested.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested.

If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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